

	Type	L #	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s
1	BRS	L15	23960	etch\$3 and ("solder bump" or bump or solder or C4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 10:12		0
2	BRS	L22	3862	15 and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 10:14		0
3	BRS	L29	1005	15 and 216/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 10:14		0
4	BRS	L36	2134	@pd <=20000531 and 22	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 10:14		0
5	BRS	L43	497	(rotat\$3 same (wafer or semeiconductor or article)) and 15	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 11:44		0
6	BRS	L50	134	43 and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 11:55		0
7	BRS	L57	26	43 and 216/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 11:55		0
8	BRS	L64	73	@pd <=20000531 and 50	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 12:01		0

	Type	L #	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s
9	BRS	L71	19	@pd <=20000531 and 57	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 12:01		0
10	BRS	L78	64	64 not 71	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 10:45		0
11	BRS	L85	152	rotat\$3 same (wafer or semeiconductor or article) same (sequential\$3 or continuous\$3 or complet\$3) and 15	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 11:47		0
12	BRS	L92	68	85 and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 11:58		0
13	BRS	L99	15	85 and 216/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 11:55		0
14	BRS	L106	61	92 not 99	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 11:58		0
15	BRS	L113	0	@pd <=20000531 and "61"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 12:01		0
16	BRS	L120	0	@pd <=20000531 and "61"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/10 12:01		0